

LM4857 Boomer® Audio Power Amplifier Series

Stereo 1.2W Audio Sub-system with 3D Enhancement

General Description

The LM4857 is an integrated audio sub-system designed for stereo cell phone applications. Operating on a 3.3V supply, it combines a stereo speaker amplifier delivering 495mW per channel into an 8Ω load, a stereo headphone amplifier delivering 33mW per channel into a 32Ω load, a mono earpiece amplifier delivering 43mW into a 32Ω load, and a line output for an external powered handsfree speaker. It integrates the audio amplifiers, volume control, mixer, power management control, and National 3D enhancement all into a single package. In addition, the LM4857 routes and mixes the stereo and mono inputs into 16 distinct output modes. The LM4857 is controlled through an $\rm I^2C$ compatible interface. Other features include an ultra-low current shutdown mode and thermal shutdown protection.

Boomer audio power amplifiers are designed specifically to provide high quality output power with a minimal amount of external components.

The LM4857 is available in a 30-bump ITL package and a 28-lead LLP package.

Key Specifications

■ P _{OUT} , Stereo Loudspeakers, 8Ω, 5V,	
1% THD+N	1.2W (typ)

P_{OUT}, Stereo Headphones, 32Ω, 5V, 1% THD+N

1% THD+N 75mW (typ)

■ P_{OUT}, Mono Earpiece, 32Ω, 5V,

1% THD+N 100mW (typ)
■ P_{OUT} , Stereo Loudspeakers, 8Ω , 3.3V,

1% THD+N 495mW (typ)

P_{OUT}, Stereo Headphones, 32Ω, 3.3V,1% THD+N33mW (typ)

P_{OUT}, Mono Earpiece, 32Ω, 3.3V,
 1% THD+N
 Shutdown Current
 43mW (typ)
 0.06μA (typ)

Features

- Stereo speaker amplifier
- Stereo headphone amplifier
- Mono earpiece amplifier
- Mono Line Output for external handsfree carkit
- Independent Left, Right, and Mono volume controls
- National 3D enhancement
- I²C compatible interface
- Ultra low shutdown current
- Click and Pop Suppression circuit
- 16 distinct output modes
- Thermal Shutdown Protection
- Available in micro SMD and LLP packages

Applications

- Cell Phones
- PDAs
- Portable Gaming Devices
- Internet Appliances
- Portable DVD/CD/AAC/MP3 players

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Typical Application

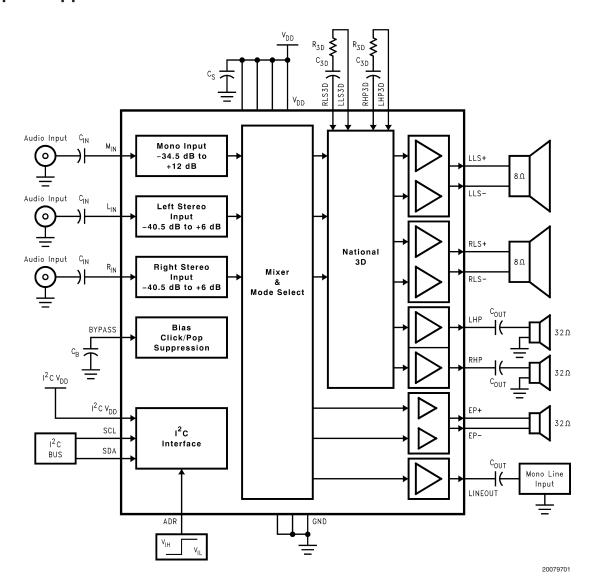
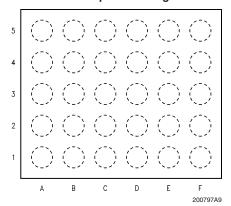


FIGURE 1. Typical Audio Amplifier Application Circuit

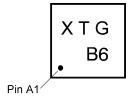
Connection Diagrams

30 Bump ITL Package



Top View (Bump-side down) Order Number LM4857ITL See NS Package Number TLA30CZA

micro SMD Marking

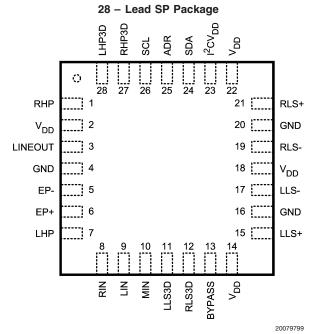


Top View
X — Date Code
T — Die Traceability
G — Boomer Family
B6 — LM4857ITL

Pin Connection (ITL)

Pin	Name	Pin Description
A1	RLS-	Right Loudspeaker Negative Output
A2	V_{DD}	Power Supply
A3	SDA	Data
A4	RHP3D	Right Headphone 3D
A5	RHP	Right Headphone Output
B1	GND	Ground
B2	I ² CV _{DD}	I ² C Interface Power Supply
B3	ADR	I ² C Address Select
B4	LHP3D	Left Headphone 3D
B5	V_{DD}	Power Supply
C1	RLS+	Right Loudspeaker Positive Output
C2	NC	No Connect
C3	SCL	Clock
C4	LINEOUT	Mono Line Output
C5	GND	Ground
D1	LLS+	Left Loudspeaker Positive Output
D2	V_{DD}	Power Supply
D3	M _{IN}	Mono Input
D4	NC	No Connect
D5	EP-	Mono Earpiece Negative Output
E1	GND	Ground
E2	BYPASS	Half-supply bypass
E3	LLS3D	Left Loudspeaker 3D
E4	R _{IN}	Right Stereo Input
E5	EP+	Mono Earpiece Positive Output
F1	LLS-	Left Loudspeaker Negative Output
F2	V_{DD}	Power Supply
F3	RLS3D	Right Loudspeaker 3D
F4	L _{IN}	Left Stereo Input
F5	LHP	Left Headphone Output

Connection Diagram



Top View Order Number LM4857SP See NS Package Number SPA28A (available soon)

Absolute Maximum Ratings (Notes 1, 2)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/ Distributors for availability and specifications.

Supply Voltage 6.0VStorage Temperature $-65^{\circ}C$ to $+150^{\circ}C$ Input Voltage -0.3V to V_{DD}

+0.3V

Power Dissipation (Note 3) Internally Limited ESD Susceptibility (Note 4) 2000V ESD Susceptibility (Note 5) 200V

Junction Temperature (T_J)

Thermal Resistance

 θ_{JA} (TLA30CZA) (Note 10) 62°C/W

Operating Ratings

Temperature Range

 $T_{MIN} \le T_A \le T_{MAX} \qquad \qquad -40^{\circ}C \le T_A \le +85^{\circ}C$

Supply Voltage

 $2.7 \text{V} \leq \text{V}_{\text{DD}} \leq 5.5 \text{V}$

 $2.5V \leq I^2CV_{DD} \leq 5.5V$

Audio Amplifier Electrical Characteristics $V_{DD} = 5.0V$ (Notes 1, 2)

The following specifications apply for $V_{DD} = 5.0V$, unless otherwise specified. Limits apply for $T_A = 25$ °C.

150°C

Symbol	Parameter	Conditions	LI	Units	
		Тур		Limits (Notes	(Limits)
			(Note 6)	7, 8)	
		V _{IN} = 0V, No load;			
		LD5 = RD5 = 0 (Note 9)			
DD	Supply Current	Mode 1, 6, 11	6	9.5	mA (max)
		Mode 4, 5, 9, 10, 14, 15	5	8	mA (max)
		Mode 2, 3, 7, 8, 12, 13	13	21	mA (max)
I _{SD}	Shutdown Current	Output mode 0 (Note 9)	0.2	3	μΑ (max)
		Speaker; THD+N = 1%; f = 1kHz; 8Ω BTL	1.2	0.9	W (min)
Po	Output Power	Headphone; THD+N = 1%; $f = 1kHz$; 32Ω SE	75	60	mW (min)
		Earpiece; THD+N = 1%; $f = 1kHz$; 32Ω BTL, CD4 = 0	100	80	mW (min)
		Earpiece; THD+N = 1%; f = 1kHz; 32Ω BTL, CD4 = 1	135		mW
		LD5 = RD5 = 0			
		Speaker; P_O = 400mW; f = 1kHz; 8Ω BTL	0.05		%
THD+N	Total Harmonic Distortion Plus	Headphone; $P_O = 15$ mW; $f = 1$ kHz; 32Ω SE	0.04		%
	Noise	Earpiece; P_O = 15mW; f = 1kHz; 32 Ω BTL, CD4 = 0	0.05		%
		Line Out, $V_O = 1V_{RMS}$; f = 1kHz; 5k Ω SE	0.009		%
	04	Speaker; LD5 = RD5 = 0	5	40	mV (max)
V _{os}	Offset Voltage	Earpiece; LD5 = RD5 = 0	5	30	mV (max)

Audio Amplifier Electrical Characteristics $V_{DD} = 5.0V$ (Notes 1, 2) (Continued) The following specifications apply for $V_{DD} = 5.0V$, unless otherwise specified. Limits apply for $T_A = 25^{\circ}C$.

Symbol	Parameter	Conditions	LI	Units	
			Typical	Limits (Notes	(Limits)
			(Note 6)	7, 8)	
		A-weighted, 0dB gain; (Note 11)			
		LD5 = RD5 = 0; Audio Inputs Terminated			
		Speaker; Mode 2, 3, 7, 8	27		μV
		Speaker; Mode 12, 13	38		μV
		Headphone; Mode 3, 4, 8, 9	10		μV
.I	Output Noice	Headphone; Mode 13, 14	14		μV
N _{OUT}	Output Noise	Earpiece; Mode 1; CD4 = 0	13		μV
		Earpiece; Mode 6	18		μV
		Earpiece; Mode 11	21		μV
		Line Out; Mode 5	11		μV
		Line Out; Mode 10	14		μV
		Line Out; Mode 15	17		μV
		$f = 217Hz; V_{rip} = 200mV_{pp}; C_B = 2.2\mu F;$			
		0dB gain; (Note 11)			
		LD5 = RD5 = 0; Audio Inputs Terminated			
		Speaker; Mode 2, 3, 7, 8	70		dB
		Speaker; Mode 12, 13,	64	54	dB (min)
		Headphone; Mode 3, 4, 8, 9	86		dB
PSRR	Power Supply Rejection Ratio	Headphone; Mode 13, 14	73	60	dB (min)
		Earpiece; Mode1	75		dB
		Earpiece; Mode 6	70		dB
		Earpiece; Mode 11	66	57	dB (min)
		Line Out; Mode 5	86		dB
		Line Out; Mode 10	74		dB
		Line Out; Mode 15	68	57	dB (min)
		LD5 = RD5 = 0			
		Loudspeaker; P _O = 400mW;	0.5		-ID
Xtalk	Crosstalk	f = 1kHz	85		dB
		Headphone; P _O = 15mW;	0.5		۵D
		f = 1kHz	85		dB
	Make up Time	CD5 = 0; C _B = 2.2µF	120		ms
Γ _{WU}	Wake-up Time	CD5 = 1; C _B = 2.2µF	230		ms

Audio Amplifier Electrical Characteristics $V_{DD} = 3.0V$ (Notes 1, 2) The following specifications apply for $V_{DD} = 3.0V$, unless otherwise specified. Limits apply for $T_A = 25\,^{\circ}C$.

Symbol	Parameter	Conditions	LM4857		Units
			Typical	Limits (Notes	(Limits)
			(Note 6)	7, 8)	
		V _{IN} = 0V, No load;			
		LD5 = RD5 = 0 (Note 9)			
I_{DD}		Mode 1, 6, 11	5.5	9	mA (max)
		Mode 4, 5, 9, 10, 14, 15	4.5	7.5	mA (max)
		Mode 2, 3, 7, 8, 12, 13	11.2	19	mA (max)
I _{SD}	Shutdown Current	Mode 0 (Note 9)	0.06	2.5	μΑ (max)

Audio Amplifier Electrical Characteristics $V_{DD} = 3.0V$ (Notes 1, 2) (Continued) The following specifications apply for $V_{DD} = 3.0V$, unless otherwise specified. Limits apply for $T_A = 25$ °C.

Symbol	Parameter	Conditions	L	Units	
			Typical (Note 6)	Limits (Notes 7, 8)	(Limits)
		Speaker; THD+N = 1%;	400	320	mW (min)
		f = 1kHz; 8Ω BTL	1.00	323	,
		Headphone; THD+N = 1%;	25	20	mW (min)
0	Output Power	f = 1kHz; 32Ω SE			
Ü	·	Earpiece; THD+N = 1%;	30	22	mW (min)
		f = 1 kHz; 32Ω BTL; CD4 = 0			
		Earpiece; THD+N = 1%;	30		mW
		f = 1kHz; 32Ω BTL; CD4 = 1			
		LD5 = RD5 = 0			
		Speaker; P_O = 200mW; f = 1kHz; 8Ω BTL	0.05		%
THD+N	Total Harmonic Distortion Plus	Headphone; $P_O = 10$ mW; $f = 1$ kHz; 32Ω SE	0.04		%
	Noise	Earpiece; P _O =10mW;			
		$f = 1 \text{kHz}$; 32Ω BTL; CD4 = 0	0.06		%
		Line Out; V _O = 1V _{BMS} ;	0.015		0/
		$f = 1kHz$; $5k\Omega$ SE	0.015		%
.,	0#+ \/-\	Speaker; LD5 = RD5 = 0	5	40	mV (max)
V _{os}	Offset Voltage	Earpiece; LD5 = RD5 = 0	5	30	mV (max)
		A-weighted; 0dB gain; (Note 11)			
		LD5 = RD5 = 0; All Inputs Terminated			
		Speaker; Mode 2, 3, 7, 8	27		μV
		Speaker; Mode 12, 13	38		μV
		Headphone; Mode 3, 4, 8, 9	10		μV
		Headphone; Mode 13, 14	14		μV
N_{OUT}	Output Noise	Earpiece; Mode 1	13		μV
		Earpiece; Mode 6	18		μV
		Earpiece; Mode 11	21		μV
		Line Out; Mode 5	11		μV
		Line Out; Mode 10	14		μV
		Line Out; Mode 15	17		μV
		$f = 217Hz$, $V_{rip} = 200mV_{pp}$; $C_B = 2.2\mu F$;			
		0dB gain; (Note 11)			
		LD5 = RD5 = 0; All Audio Inputs			
		Terminated			
		Speaker; Mode 2, 3, 7, 8	70		dB
		Speaker; Mode 12, 13,	65	55	dB (min)
PSRR	Power Supply Rejection Ratio	Headphone; Mode 3, 4, 8, 9	87		dB
JHH	i owei Suppiy nejection natio	Headphone; Mode 13, 14	75	62	dB (min)
		Earpiece; Mode1	76		dB
		Earpiece; Mode 6	70		dB
		Earpiece; Mode 11	67	57	dB (min)
		Line Out; Mode 5	88		dB
		Line Out; Mode 10	74		dB
		Line Out; Mode 15	71	58	dB (min)

Audio Amplifier Electrical Characteristics $V_{DD} = 3.0V$ (Notes 1, 2) (Continued) The following specifications apply for $V_{DD} = 3.0V$, unless otherwise specified. Limits apply for $T_A = 25$ °C.

Symbol	Parameter	Conditions	LM4857		Units
			Typical	Limits (Notes	(Limits)
			(Note 6)	7, 8)	
		LD5 = RD5 = 0			
VI-II.	0	Loudspeaker; P _O = 200mW;	82		dB
Xtalk	Crosstalk	f = 1kHz			
		Headphone; P _O = 10mW; f = 1kHz	82		dB
T _{wu}	Wake-up Time	CD5 = 0; $C_B = 2.2\mu F$	80		ms
	wake-up time	CD5 = 1; C _B = 2.2µF	140		ms

Volume Control Electrical Characteristics (Notes 1, 2)

The following specifications apply for V_{DD} = 5.0V and V_{DD} = 3.0V, unless otherwise specified. Limits apply for T_A = 25°C.

Symbol	Parameter	Conditions	LI	LM4857		
			Typical	Limits (Notes	(Limits)	
			(Note 6)	7, 8)		
		maximum gain setting	6	5.5	dB (min)	
	Stereo Volume Control Range			6.5	dB (max)	
	Stereo Volume Control Hange	minimum gain setting	-40.5	-41	dB (min)	
				-40	dB (max)	
		maximum gain setting	12	11.5	dB (min)	
	Mono Volume Control Range			12.5	dB (max)	
		minimum gain setting	-34.5	-35	dB (min)	
				-34	dB (max)	
	Volume Control Step Size		1.5		dB	
	Volume Control Step Size Error		+/-0.2	+/-0.5	dB (max)	
	Stereo Channel to Channel Gain Mismatch		0.3		dB	
		Mode 12, V _{in} = 1V _{RMS}				
	Mute Attenuation	Headphone	85		dB	
		Line Out	85		dB	
		maximum gain setting	33.5	25	kΩ (min)	
	L and D. Input Impedance			42	$k\Omega$ (max)	
	L _{IN} and R _{IN} Input Impedance	minimum gain setting	100	75	kΩ (min)	
				125	$k\Omega$ (max)	
	M _{IN} Input Impedance	maximum gain setting	20	15	kΩ (min)	
				25	$k\Omega$ (max)	
		minimum gain setting	98	73	kΩ (min)	
				123	$k\Omega$ (max)	

Control Interface Electrical Characteristics (Notes 1, 2)

The following specifications apply for V_{DD} = 5V and V_{DD} = 3V and 2.5V \leq $I^2CV_{DD} \leq$ 5.5V, unless otherwise specified. Limits apply for $T_A = 25$ °C.

Symbol	Parameter	Conditions	LM4857		Units
			Typical	Limits (Notes	(Limits)
			(Note 6)	7, 8)	
t ₁	SCL period			2.5	μs (min)
t ₂	SDA Set-up Time			100	ns (min)
t ₃	SDA Stable Time			0	ns (min)
t ₄	Start Condition Time			100	ns (min)

Control Interface Electrical Characteristics (Notes 1, 2) (Continued)

The following specifications apply for V_{DD} = 5V and V_{DD} = 3V and 2.5V \leq $I^2CV_{DD} \leq$ 5.5V, unless otherwise specified. Limits apply for T_A = 25°C.

Symbol	Parameter	Conditions	LM4857		Units
			Typical Limits (Notes		(Limits)
			(Note 6)	7, 8)	
t ₅	Stop Condition time			100	ns (min)
V _{IH}	Digital Input High Voltage			0.7 x I ² CVDD	V (min)
V _{IL}	Digital Input Low Voltage			0.3 x I ² CV _{DD}	V (max)

Note 1: All voltages are measured with respect to the GND pin unless otherwise specified.

Note 2: Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional but do not guarantee specific performance limits. Electrical Characteristics state DC and AC electrical specifications under particular test conditions which guarantee specific performance limits. This assumes that the device is within the Operating Ratings. Specifications are not guaranteed for parameters where no limit is given, however, the typical value is a good indication of device performance.

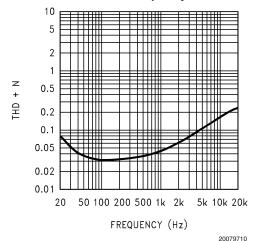
Note 3: The maximum power dissipation must be derated at elevated temperatures and is dictated by T_{JMAX} , θ_{JA} , and the ambient temperature, T_A . The maximum allowable power dissipation is $P_{DMAX} = (T_{JMAX} - T_A) / \theta_{JA}$ or the number given in Absolute Maximum Ratings, whichever is lower. For the LM4857 operating in Mode 3, 8, or 13 with $V_{DD} = 5V$, 8Ω stereo loudspeakers and 32Ω stereo headphones, the total power dissipation is 1.348W. $\theta_{JA} = 62$ °C/W.

- Note 4: Human body model, 100pF discharged through a $1.5k\Omega$ resistor.
- Note 5: Machine Model, 220pF-240pF discharged through all pins.
- Note 6: Typicals are measured at +25°C and represent the parametric norm.
- Note 7: Limits are guaranteed to National's AOQL (Average Outgoing Quality Level).
- Note 8: Datasheet min/max specification limits are guaranteed by design, test, or statistical analysis.
- Note 9: Shutdown current and supply current are measured in a normal room environment. All digital input pins are connected to I²CV_{DD}.
- Note 10: The given θ_{JA} is for an LM4857ITL mounted on a PCB with a 2in^2 area of 1oz printed circuit board copper ground plane.
- Note 11: "0dB gain" refers to the volume control gain setting of M_{IN}, L_{IN}, and R_{IN} set at 0dB.

Exte	External Components Description					
Com	ponents	Functional Description				
1.	C _{IN}	This is the input coupling capacitor. It blocks the DC voltage and couples the input signal to the amplifier's input terminals. C_{IN} also creates a highpass filter with the internal resistor R_i (Input Impedance) at $f_c = 1/(2\pi R_i C_{IN})$.				
2.	Cs	This is the supply bypass capacitor. It filters the supply voltage applied to the V_{DD} pin and helps reduce the noise at the V_{DD} pin.				
3.	Св	This is the BYPASS pin capacitor. It filters the $V_{\rm DD}$ / 2 voltage and helps maintain the LM4857's PSRR.				
4.	Соит	This is the output coupling capacitor. It blocks the DC voltage and couples the output signal to the speaker load R_L . C_{OUT} also creates a high pass filter with R_L at $f_O = 1/(2\pi R_L C_{OUT})$.				
5.	R _{3D}	This resistor sets the gain of the National 3D effect. Please refer to the National 3D Enhancement section for information on selecting the value of R _{3D} .				
6.	C _{3D}	This capacitor sets the frequency at which the National 3D effect starts to occur. Please refer to the National 3D Enhancement section for information on selecting the value of C_{3D} .				

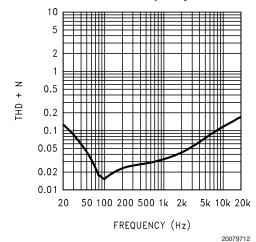
Typical Performance Characteristics (Note 11)





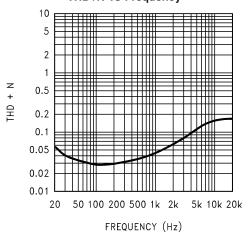
 V_{DD} = 5V; LLS, RLS; P_O = 400mW; R_L = 8 Ω ; Mode 7; 0dB Gain

THD+N vs Frequency



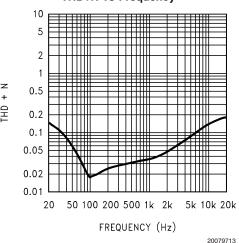
 V_{DD} = 5V; LHP, RHP; P_{O} = 15mW; R_{L} = 32 Ω ; Mode 9; 0dB Gain

THD+N vs Frequency



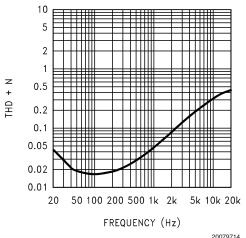
 $\begin{aligned} \textbf{V}_{\text{DD}} &= 3 \text{V}; \text{ LLS, RLS; P}_{\text{O}} &= 200 \text{mW;} \\ \textbf{R}_{\text{L}} &= 8 \Omega; \text{ Mode 7; 0dB Gain} \end{aligned}$

THD+N vs Frequency



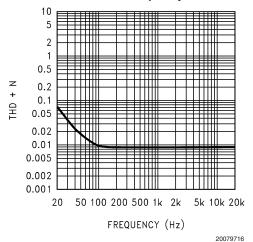
 V_{DD} = 3V; LHP, RHP; P_{O} = 10mW; R_{L} = 32 Ω ; Mode 9; 0dB Gain

THD+N vs Frequency



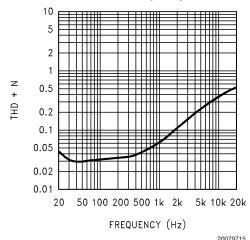
 $V_{DD} = 5V; \ EP; \ P_O = 15mW;$ $R_L = 32\Omega; \ Mode \ 1; \ 0dB \ Gain, \ CD4 = 0$

THD+N vs Frequency



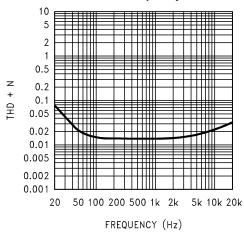
 V_{DD} = 5V; LINEOUT; V_{O} = 1 V_{RMS} ; R_{L} = 5k Ω ; Mode 5; 0dB Gain

THD+N vs Frequency



 $V_{DD} = 3V; \; EP; \; P_O = 10mW; \\ R_L = 32\Omega; \; Mode \; 1; \; 0dB \; Gain, \; CD4 = 0$

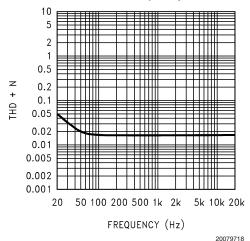
THD+N vs Frequency



 V_{DD} = 3V; LINEOUT; V_{O} = 1 V_{RMS} ; R_{L} = 5k Ω ; Mode 5; 0dB Gain

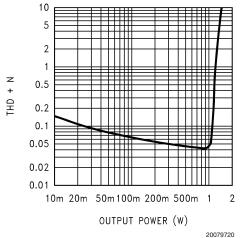
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THD+N vs Frequency



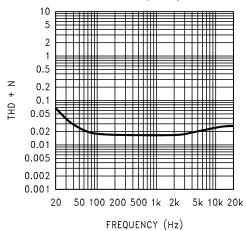
 $V_{DD} = 5V$; LINEOUT; $V_{O} = 1V_{RMS}$; $R_{L} = 5k\Omega$; Mode 10; 0dB Gain

THD+N vs Output Power



 V_{DD} = 5V; LLS, RLS; f = 1kHz; R_L = 8 Ω ; Mode 7; 0dB Gain

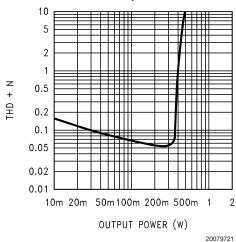
THD+N vs Frequency



 V_{DD} = 3V; LINEOUT; V_{O} = 1 V_{RMS} ; R_{L} = 5k Ω ; Mode 10; 0dB Gain

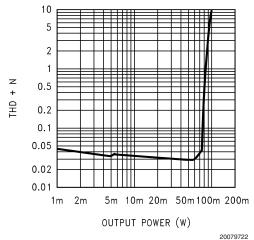
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THD+N vs Output Power



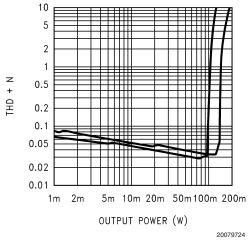
 V_{DD} = 3V; LLS, RLS; f = 1kHz; R_L = 8 Ω ; Mode 7; 0dB Gain

THD+N vs Output Power



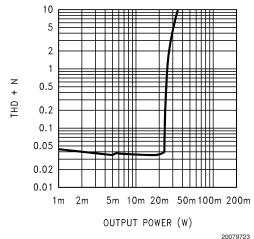
 V_{DD} = 5V; LHP, RHP; f = 1kHz; R_L = 32 Ω ; Mode 9; 0dB Gain

THD+N vs Output Power



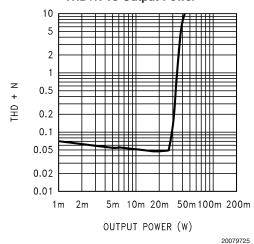
 $\label{eq:VDD} \begin{aligned} \text{V}_{\text{DD}} &= 5\text{V}; \text{ EP}; \text{ f} = 1\text{kHz}; \text{ R}_{\text{L}} = 32\Omega; \\ \text{Mode 1; 0dB Gain; Top-CD4} &= 1; \text{ Bot-CD4} = 0 \end{aligned}$

THD+N vs Output Power



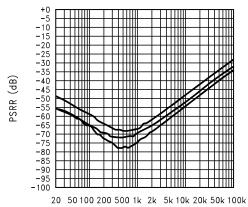
 V_{DD} = 3V; LHP, RHP; f = 1kHz; R_L = 32 Ω ; Mode 9; 0dB Gain

THD+N vs Output Power



 V_{DD} = 3V; EP; f = 1kHz; R_L = 32 Ω ; Mode 1; 0dB Gain



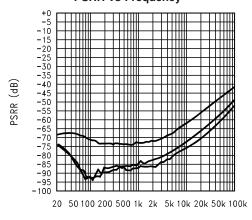


FREQUENCY (Hz)

20079726

 V_{DD} = 5V; LLS, RLS; R_L = 8 Ω ; 0db Gain; All audio inputs terminated Top-Mode 12, 13; Mid-Mode 2, 3; Bot-Mode 7, 8

PSRR vs Frequency

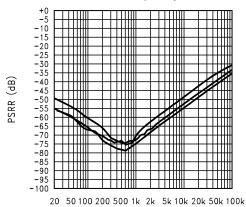


FREQUENCY (Hz)

20079728

 V_{DD} = 5V; LHP, RHP; R_L = 32 Ω ; 0db Gain; All audio inputs terminated Top-Mode 13, 14; Mid-Mode 3, 4; Bot-Mode 8, 9

PSRR vs Frequency

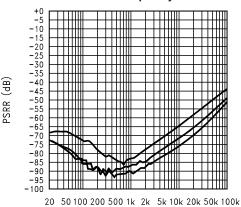


FREQUENCY (Hz)

20079727

 V_{DD} = 3V; LLS, RLS; R_L = 8 Ω ; 0db Gain; All audio inputs terminated Top-Mode 12, 13; Mid-Mode 2, 3; Bot-Mode 7, 8

PSRR vs Frequency

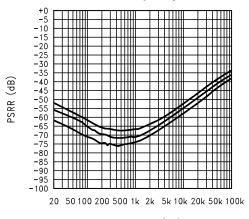


FREQUENCY (Hz)

20079729

 V_{DD} = 3V; LHP, RHP; R_L = 32 Ω ; 0db Gain; All audio inputs terminated Top-Mode 13, 14; Mid-Mode 3, 4; Bot-Mode 8, 9

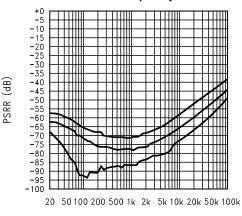
PSRR vs Frequency



FREQUENCY (Hz)

 V_{DD} = 5V; EP; R_L = 32 Ω ; 0db Gain; All audio inputs terminated Top-Mode 11; Mid-Mode 6; Bot-Mode 1

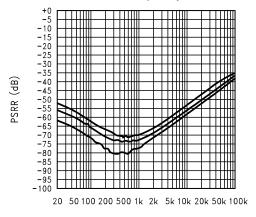
PSRR vs Frequency



 V_{DD} = 5V; LINEOUT; R_L = 5k Ω ; 0db Gain; All audio inputs terminated Top-Mode 15; Mid-Mode 10; Bot-Mode 5

FREQUENCY (Hz)

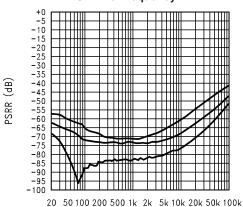
PSRR vs Frequency



FREQUENCY (Hz)

 V_{DD} = 3V; EP; R_L = 32 Ω ; 0db Gain; All audio inputs terminated Top-Mode 11; Mid-Mode 6; Bot-Mode 1

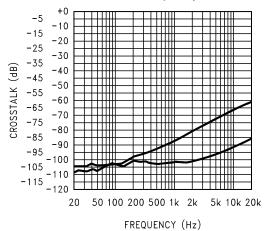
PSRR vs Frequency



FREQUENCY (Hz)

 V_{DD} = 3V; LINEOUT; R_L = 5k Ω ; 0db Gain; All audio inputs terminated Top-Mode 15; Mid-Mode 10; Bot-Mode 5

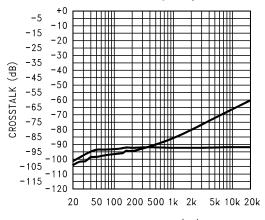
Crosstalk vs Frequency



 $V_{DD} = 5V$; LLS, RLS; $P_O = 400$ mW; $R_L = 8\Omega$; Mode 7; 0db Gain; 3D off Top-Left to Right; Bot- Right to Left

20079734

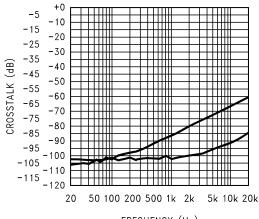
Crosstalk vs Frequency



FREQUENCY (Hz)

20079736 $V_{DD} = 5V$; LHP, RHP; $P_O = 15$ mW; $R_L = 32\Omega$; Mode 9; 0db Gain; 3D off Top-Left to Right; Bot- Right to Left

Crosstalk vs Frequency

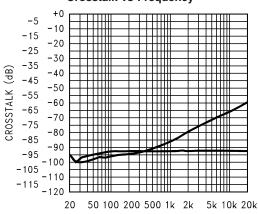


FREQUENCY (Hz)

20079735

 V_{DD} = 3V; LLS, RLS; P_{O} = 200mW; R_{L} = 8Ω ; Mode 7; 0db Gain; 3D off Top-Left to Right; Bot- Right to Left

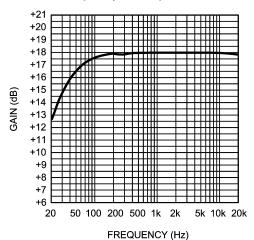
Crosstalk vs Frequency



FREQUENCY (Hz)

 V_{DD} = 3V; LHP, RHP; P_O = 10mW; R_L = 32 Ω ; Mode 9; 0db Gain; 3D off Top-Left to Right; Bot- Right to Left

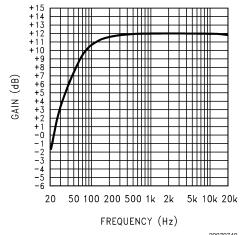
Frequency vs Response



20079738 DI C. D. — 90.

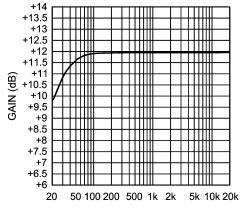
LLS, RLS; $R_L = 8\Omega$; Mode 2; Full Gain

Frequency vs Response



LHP, RHP; $R_L = 32\Omega$; $C_O = 100 \mu F$ Mode 4; Full Gain

Frequency vs Response

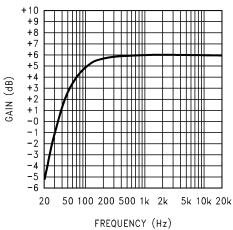


FREQUENCY (Hz)

20079739

LLS, RLS; $R_L = 8\Omega$; Mode 7; Full Gain

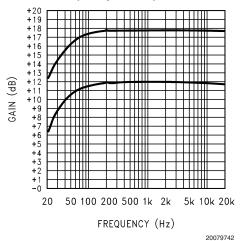
Frequency vs Response



20079741

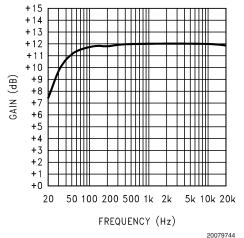
LHP, RHP; R_L = 32Ω ; C_O = 100μ F Mode 9; Full Gain

Frequency vs Response



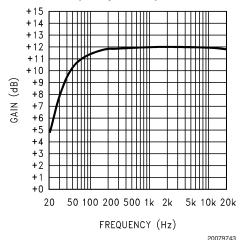
EP; $R_L = 32\Omega$; Mode 1; Full Gain Top-CD4 = 1; Bot-CD4 = 0

Frequency vs Response



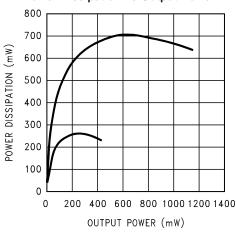
LINEOUT; $R_L = 5k\Omega$; $C_O = 2.2\mu F$ Mode 10; Full Gain

Frequency vs Response



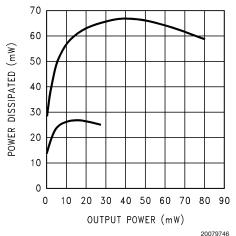
LINEOUT; $R_L = 5k\Omega$; $C_O = 2.2\mu F$ Mode 5; Full Gain

Power Dissipation vs Output Power



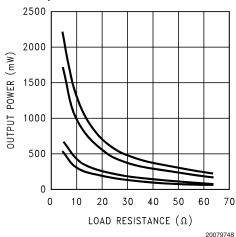
LLS, RLS; R_L = 8Ω ; THD+N $\leq 1\%$ Top-V_{DD} = 5V; Bot-V_{DD} = 3V
per channel

Power Dissipation vs Output Power



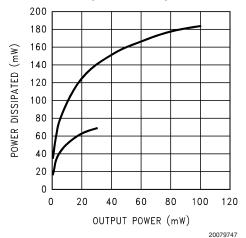
LHP, RHP; $R_L = 32\Omega$; THD+N $\leq 1\%$ Top-V_{DD} = 5V; Bot-V_{DD} = 3V per channel

Output Power vs Load Resistance



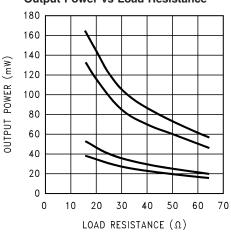
 $LLS,~RLS;~R_L=8\Omega;\\ Top-V_{DD}=5V,~10\%~THD+N;~Topmid-V_{DD}=5V,~1\%~THD+N;\\ Botmid-V_{DD}=3V,~10\%~THD+N;~Bot-V_{DD}=3V,~1\%~THD+N \\$

Power Dissipation vs Output Power



EP; $R_L = 32\Omega$; THD+N $\leq 1\%$ Top-V_{DD} = 5V; Bot-V_{DD} = 3V

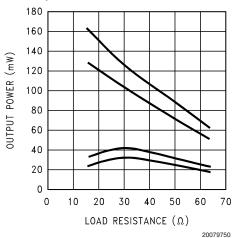
Output Power vs Load Resistance



LHP, RHP; $R_L = 32\Omega$;

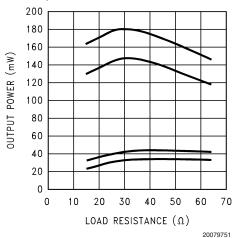
Top- V_{DD} = 5V, 10% THD+N; Topmid- V_{DD} = 5V, 1% THD+N; Botmid- V_{DD} = 3V, 10% THD+N; Bot- V_{DD} = 3V, 1% THD+N

Output Power vs Load Resistance



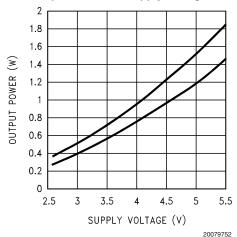
EP; R_L = 32Ω ; CD4 = 0 Top-V_{DD} = 5V, 10% THD+N; Topmid-V_{DD} = 5V, 1% THD+N; Botmid-V_{DD} = 3V, 10% THD+N; Bot-V_{DD} = 3V, 1% THD+N

Output Power vs Load Resistance



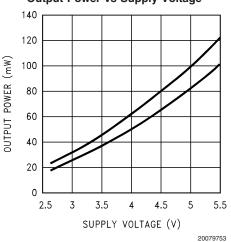
EP; R_L = 32Ω ; CD4 = 1 Top-V_{DD} = 5V, 10% THD+N; Topmid-V_{DD} = 5V, 1% THD+N; Botmid-V_{DD} = 3V, 10% THD+N; Bot-V_{DD} = 3V, 1% THD+N

Output Power vs Supply Voltage



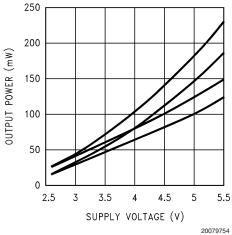
LLS, RLS; R_L = 8Ω ; Top-10% THD+N; Bot-1% THD+N

Output Power vs Supply Voltage



LHP, RHP; R $_{\rm L}$ = 32 $\!\Omega;$ Top-10% THD+N; Bot-1% THD+N

Output Power vs Supply Voltage



 $\label{eq:energy} \text{EP; R}_{\text{L}} = 32\Omega;$ Top–10% THD+N; CD4 = 1; Topmid–1% THD+N, CD4 = 1 Botmid-10% THD+N; CD4 = 0; Bot-1% THD+N, CD4 = 0

Application Information

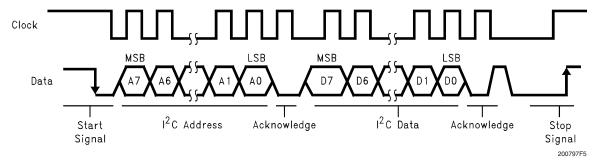


FIGURE 2. I²C Bus Format

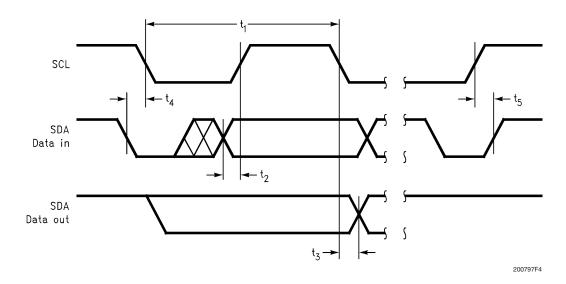


FIGURE 3. I²C Timing Diagram

TABLE 1. Chip Address

	A7	A6	A 5	A 4	A3	A2	A1	Α0
Chip Address	1	1	1	1	1	0	EC	0
ADR = 0	1	1	1	1	1	0	0	0
ADR = 1	1	1	1	1	1	0	1	0

EC - externally configured by ADR pin

TABLE 2. Control Registers

	D7	D6	D5	D4	D3	D2	D1	D0
Mono Volume control	0	0	0	MD4	MD3	MD2	MD1	MD0
Left Volume control	0	1	LD5	LD4	LD3	LD2	LD1	LD0
Right Volume control	1	0	RD5	RD4	RD3	RD2	RD1	RD0
Mode control	1	1	CD5	CD4	CD3	CD2	CD1	CD0

TABLE 3. Mono Volume Control

MD4	MD3	MD2	MD1	MD0	Gain (dB)
0	0	0	0	0	-34.5
0	0	0	0	1	-33.0
0	0	0	1	0	-31.5
0	0	0	1	1	-30.0
0	0	1	0	0	-28.5
0	0	1	0	1	-27.0
0	0	1	1	0	-25.5
0	0	1	1	1	-24.0
0	1	0	0	0	-22.5
0	1	0	0	1	-21.0
0	1	0	1	0	-19.5
0	1	0	1	1	-18.0
0	1	1	0	0	-16.5
0	1	1	0	1	-15.0
0	1	1	1	0	-13.5
0	1	1	1	1	-12.0
1	0	0	0	0	-10.5
1	0	0	0	1	-9.0
1	0	0	1	0	-7.5
1	0	0	1	1	-6.0
1	0	1	0	0	-4.5
1	0	1	0	1	-3.0
1	0	1	1	0	-1.5
1	0	1	1	1	0.0
1	1	0	0	0	1.5
1	1	0	0	1	3.0
1	1	0	1	0	4.5
1	1	0	1	1	6.0
1	1	1	0	0	7.5
1	1	1	0	1	9.0
1	1	1	1	0	10.5
1	1	1	1	1	12.0

TABLE 4. Stereo Volume Control

LD4//RD4	LD3//RD3	LD2//RD2	LD1//RD1	LD0//RD0	Gain (dB)
0	0	0	0	0	-40.5
0	0	0	0	1	-39.0
0	0	0	1	0	-37.5
0	0	0	1	1	-36.0
0	0	1	0	0	-34.5
0	0	1	0	1	-33.0
0	0	1	1	0	-31.5
0	0	1	1	1	-30.0
0	1	0	0	0	-28.5
0	1	0	0	1	-27.0
0	1	0	1	0	-25.5
0	1	0	1	1	-24.0
0	1	1	0	0	-22.5
0	1	1	0	1	-21.0
0	1	1	1	0	-19.5
0	1	1	1	1	-18.0
1	0	0	0	0	-16.5
1	0	0	0	1	-15.0
1	0	0	1	0	-13.5
1	0	0	1	1	-12.0
1	0	1	0	0	-10.5
1	0	1	0	1	-9.0
1	0	1	1	0	-7.5
1	0	1	1	1	-6.0
1	1	0	0	0	-4.5
1	1	0	0	1	-3.0
1	1	0	1	0	-1.5
1	1	0	1	1	0.0
1	1	1	0	0	1.5
1	1	1	0	1	3.0
1	1	1	1	0	4.5
1	1	1	1	1	6.0

TABLE 5. Mixer and Output Mode Control

Mode	CD3	CD2	CD1	CD0	Mono	Mono Ea	rpiece	Loudspeaker	Loudspeaker	Headphone	Headphone
					Line Out	(CD4 = 0)	(CD4 =	L	R	L	R
							1)				
0	0	0	0	0	SD	SD	SD	SD	SD	SD	SD
1	0	0	0	1	MUTE	(G _M x M)	2(G _M x M)	SD	SD	MUTE	MUTE
2	0	0	1	0	MUTE	SD	SD	2(G _M x M)	2(G _M x M)	MUTE	MUTE
3	0	0	1	1	MUTE	SD	SD	2(G _M x M)	2(G _M x M)	(G _M x M)	(G _M x M)
4	0	1	0	0	MUTE	SD	SD	SD	SD	(G _M x M)	(G _M x M)
5	0	1	0	1	(G _M x M)	SD	SD	SD	SD	MUTE	MUTE
6	0	1	1	0	MUTE	(G _L x L) + (G _R x R)	2(G _L x L) + 2(G _R x R)	SD	SD	MUTE	MUTE
7	0	1	1	1	MUTE	SD	SD	2(G _L x L)	2(G _R x R)	MUTE	MUTE
8	1	0	0	0	MUTE	SD	SD	2(G _L x L)	2(G _R x R)	(G _L x L)	(G _R x R)
9	1	0	0	1	MUTE	SD	SD	SD	SD	(G _L x L)	(G _R x R)
10	1	0	1	0	$(G_L \times L) + (G_R \times R)$	SD	SD	SD	SD	MUTE	MUTE
11	1	0	1	1	MUTE	$(G_{M} \times M) + (G_{L} \times L) + (G_{R} \times R)$	$2(G_{M} \times M) + 2(G_{L} \times L) + 2(G_{R} \times R)$	SD	SD	MUTE	MUTE
12	1	1	0	0	MUTE	SD	SD	2(G _L x L) + 2(G _M x M)	2(G _R x R) + 2(G _M x M)	MUTE	MUTE
13	1	1	0	1	MUTE	SD	SD	2(G _L x L) + 2(G _M x M)	2(G _R x R) + 2(G _M x M)	(G _L x L) + (G _M x M)	(G _R x R) + (G _M x M)
14	1	1	1	0	MUTE	SD	SD	SD	SD	(G _L x L) + (G _M x M)	(G _R x R) + (G _M x M)
15	1	1	1	1	(G _M x M) +(G _L x L) +(G _R x R)	SD	SD	SD	SD	MUTE	MUTE

M - M_{IN} Input Level L - L_{IN} Input Level

R - R_{IN} Input Level

G_M - Mono Volume Control Gain G_L - Left Stereo Volume Control Gain

G_R - Right Stereo Volume Control Gain SD - Shutdown

MUTE - Mute

TABLE 6. National 3D Enhancement

LD5	0	Loudspeaker National 3D Off
LDS	1	Loudspeaker National 3D On
RD5	0	Headphone National 3D Off
NDS	1	Headphone National 3D Off

TABLE 7. Wake-up Time Select

CD5	0	Fast Wake-up Setting
CDS	1	Slow Wake-up Setting

TABLE 8. Earpiece Amplifier Gain Select

CD4	0	0dB Earpiece Output Stage Gain Setting
CD4	1	6dB Earpiece Output Stage Gain Setting

I²C COMPATIBLE INTERFACE

The LM4857 uses a serial bus, which conforms to the I²C protocol, to control the chip's functions with two wires: clock (SCL) and data (SDA). The clock line is uni-directional. The data line is bi-directional (open-collector). The maximum clock frequency specified by the I²C standard is 400kHz. In this discussion, the master is the controlling microcontroller and the slave is the LM4857.

The I^2C address for the LM4857 is determined using the ADR pin. The LM4857's two possible I^2C chip addresses are of the form 111110 X_1O (binary), where $X_1=0$, if ADR is logic low; and $X_1=1$, if ADR is logic high. If the I^2C interface is used to address a number of chips in a system, the LM4857's chip address can be changed to avoid any possible address conflicts.

The bus format for the I²C interface is shown in Figure 2. The bus format diagram is broken up into six major sections:

The "start" signal is generated by lowering the data signal while the clock signal is high. The start signal will alert all devices attached to the I²C bus to check the incoming address against their own address.

The 8-bit chip address is sent next, most significant bit first. The data is latched in on the rising edge of the clock. Each address bit must be stable while the clock level is high.

After the last bit of the address bit is sent, the master releases the data line high (through a pull-up resistor). Then the master sends an acknowledge clock pulse. If the LM4857 has received the address correctly, then it holds the data line low during the clock pulse. If the data line is not held low during the acknowledge clock pulse, then the master should abort the rest of the data transfer to the LM4857.

The 8 bits of data are sent next, most significant bit first. Each data bit should be valid while the clock level is stable high.

After the data byte is sent, the master must check for another acknowledge to see if the LM4857 received the data.

If the master has more data bytes to send to the LM4857, then the master can repeat the previous two steps until all data bytes have been sent.

The "stop" signal ends the transfer. To signal "stop", the data signal goes high while the clock signal is high. The data line should be held high when not in use.

I²C INTERFACE POWER SUPPLY PIN (I²CV_{DD})

The LM4857's I^2C interface is powered up through the I^2CV_{DD} pin. The LM4857's I^2C interface operates at a voltage level set by the I^2CV_{DD} pin which can be set independent to that of the main power supply pin V_{DD} . This is ideal whenever logic levels for the I^2C interface are dictated by a microcontroller or microprocessor that is operating at a lower supply voltage than the main battery of a portable system.

NATIONAL 3D ENHANCEMENT

The LM4857 features a 3D audio enhancement effect that widens the perceived soundstage from a stereo audio signal. The 3D audio enhancement improves the apparent stereo

channel separation whenever the left and right speakers are too close to one another, due to system size constraints or equipment limitations.

An external RC network, shown in Figure 1, is required to enable the 3D effect. There are separate RC networks for both the stereo loudspeaker outputs as well as the stereo headphone outputs, so the 3D effect can be set independently for each set of stereo outputs.

The amount of the 3D effect is set by the $R_{\rm 3D}$ resistor. Decreasing the value of $R_{\rm 3D}$ will increase the 3D effect. The $C_{\rm 3D}$ capacitor sets the low cutoff frequency of the 3D effect. Increasing the value of $C_{\rm 3D}$ will decrease the low cutoff frequency at which the 3D effect starts to occur, as shown by Equation 1.

$$f_{3D(-3dB)} = 1 / 2\pi(R_{3D})(C_{3D})$$
 (1)

Activating the 3D effect will cause an increase in gain by a multiplication factor of (1 + $20k\Omega/R_{3D})$. This increase in gain is easily compensated for by adjusting the volume control accordingly. Setting $R_{3D}=20k\Omega$ and $C_{3D}=0.22\mu F$ allows the LM4857 to produce a pronounced 3D effect with a minimal increase in output noise.

PCB LAYOUT AND SUPPLY REGULATION CONSIDERATIONS FOR DRIVING 3 Ω AND 4 Ω LOADS

Power dissipated by a load is a function of the voltage swing across the load and the load's impedance. As load impedance decreases, load dissipation becomes increasingly dependent on the interconnect (PCB trace and wire) resistance between the amplifier output pins and the load's connections. Residual trace resistance causes a voltage drop, which results in power dissipated in the trace and not in the load as desired. For example, 0.1Ω trace resistance reduces the output power dissipated by a 4Ω load from 1.7W to 1.6W. The problem of decreased load dissipation is exacerbated as load impedance decreases. Therefore, to maintain the highest load dissipation and widest output voltage swing, PCB traces that connect the output pins to a load must be as wide as possible.

Poor power supply regulation adversely affects maximum output power. A poorly regulated supply's output voltage decreases with increasing load current. Reduced supply voltage causes decreased headroom, output signal clipping, and reduced output power. Even with tightly regulated supplies, trace resistance creates the same effects as poor supply regulation. Therefore, making the power supply traces as wide as possible helps maintain full output voltage swing.

BRIDGE CONFIGURATION EXPLANATION

The LM4857 consists of three sets of a bridged-tied amplifier pairs that drive the left loudspeaker (LLS), the right loudspeaker (RLS), and the mono earpiece (EP). For this discussion, only the LLS bridge-tied amplifier pair will be referred to. The LM4857 drives a load, such as a speaker, connected

between outputs, LLS+ and LLS-. In the LLS amplifier block, the output of the amplifier that drives LLS- serves as the input to the unity gain inverting amplifier that drives LLS+.

This results in both amplifiers producing signals identical in magnitude, but 180° out of phase. Taking advantage of this phase difference, a load is placed between LLS- and LLS+ and driven differentially (commonly referred to as 'bridge mode'). This results in a differential or BTL gain of:

$$A_{VD} = 2(R_f / R_i) = 2$$
 (2)

Both the feedback resistor, R_{f} , and the input resistor, R_{i} , are internally set.

Bridge mode amplifiers are different from single-ended amplifiers that drive loads connected between a single amplifier's output and ground. For a given supply voltage, bridge mode has a distinct advantage over the single-ended configuration: its differential output doubles the voltage swing across the load. Theoretically, this produces four times the output power when compared to a single-ended amplifier under the same conditions. This increase in attainable output power assumes that the amplifier is not current limited and that the output signal is not clipped.

Another advantage of the differential bridge output is no net DC voltage across the load. This is accomplished by biasing LLS- and LLS+ outputs at half-supply. This eliminates the coupling capacitor that single supply, single-ended amplifiers require. Eliminating an output coupling capacitor in a typical single-ended configuration forces a single-supply amplifier's half-supply bias voltage across the load. This increases internal IC power dissipation and may permanently damage loads such as speakers.

POWER DISSIPATION

Power dissipation is a major concern when designing a successful single-ended or bridged amplifier.

A direct consequence of the increased power delivered to the load by a bridge amplifier is higher internal power dissipation. The LM4857 has 3 sets of bridged-tied amplifier pairs driving LLS, RLS, and EP. The maximum internal power dissipation operating in the bridge mode is twice that of a single-ended amplifier. From Equation (3) and (4), assuming a 5V power supply and an 8Ω load, the maximum power dissipation for LLS and RLS is 634mW per channel. From equation (5), assuming a 5V power supply and a 32Ω load, the maximum power dissipation for EP is 158mW.

$$P_{DMAX-LLS} = 4(V_{DD})^2 I (2\pi^2 R_L)$$
: Bridged (3)

$$P_{DMAX-RLS} = 4(V_{DD})^2 I (2\pi^2 R_L)$$
: Bridged (4)

$$P_{DMAX-EP} = 4(V_{DD})^2 I (2\pi^2 R_L)$$
: Bridged (5)

The LM4857 also has 3 sets of single-ended amplifiers driving LHP, RHP, and LINEOUT. The maximum internal power dissipation for ROUT and LOUT is given by equation (6) and (7). From Equations (6) and (7), assuming a 5V power supply and a 32Ω load, the maximum power dissipation for LOUT and ROUT is 40mW per channel. From equation (8), assuming a 5V power supply and a $5k\Omega$ load, the maximum power dissipation for LINEOUT is negligible.

$$P_{DMAX-LHP} = (V_{DD})^2 / (2\pi^2 R_L)$$
: Single-ended (6)

$$P_{DMAX-RHP} = (V_{DD})^2 / (2\pi^2 R_L)$$
: Single-ended (7)

$$P_{DMAX-LINE} = (V_{DD})^2 / (2\pi^2 R_L)$$
: Single-ended (8)

The maximum internal power dissipation of the LM4857 occurs during output modes 3, 8, and 13 when both loud-speaker and headphone amplifiers are simultaneously on; and is given by Equation (9).

$$P_{DMAX-TOTAL} = \\ P_{DMAX-LLS} + P_{DMAX-RLS} + P_{DMAX-LHP} + P_{DMAX-RHP} \quad (9)$$

The maximum power dissipation point given by Equation (9) must not exceed the power dissipation given by Equation (10):

$$P_{DMAX}' = (T_{JMAX} - T_A) / \theta_{JA}$$
 (10)

The LM4857's $T_{JMAX}=150^{\circ}C$. In the ITL package, the LM4857's θ_{JA} is $62^{\circ}C/W$. At any given ambient temperature T_A , use Equation (10) to find the maximum internal power dissipation supported by the IC packaging. Rearranging Equation (10) and substituting $P_{DMAX^{-}TOTAL}$ for $P_{DMAX^{-}}$ results in Equation (11). This equation gives the maximum ambient temperature that still allows maximum stereo power dissipation without violating the LM4857's maximum junction temperature.

$$T_A = T_{JMAX} - P_{DMAX-TOTAL} \theta_{JA}$$
 (11)

For a typical application with a 5V power supply, stereo 8Ω loudspeaker load, and the stereo 32Ω headphone load, the maximum ambient temperature that allows maximum stereo power dissipation without exceeding the maximum junction temperature is approximately 66.4°C for the ITL package.

$$T_{JMAX} = P_{DMAX-TOTAL} \theta_{JA} + T_{A}$$
 (12)

Equation (12) gives the maximum junction temperature T_{J^-} MAX. If the result violates the LM4857's 150°C, reduce the maximum junction temperature by reducing the power supply voltage or increasing the load resistance. Further allowance should be made for increased ambient temperatures.

The above examples assume that a device is a surface mount part operating around the maximum power dissipation point. Since internal power dissipation is a function of output power, higher ambient temperatures are allowed as output power or duty cycle decreases. If the result of Equation (9) is greater than that of Equation (10), then decrease the supply voltage, increase the load impedance, or reduce the ambient temperature. If these measures are insufficient, a heat sink can be added to reduce $\theta_{\text{JA}}.$ The heat sink can be created using additional copper area around the package, with connections to the ground pin(s), supply pin and amplifier output pins. External, solder attached SMT heatsinks such as the Thermalloy 7106D can also improve power dissipation. When adding a heat sink, the θ_{JA} is the sum of θ_{JC} , θ_{CS} , and θ_{SA} . (θ_{JC} is the junction-to-case thermal impedance, θ_{CS} is the case-to-sink thermal impedance, and θ_{SA} is the sink-to-

ambient thermal impedance.) Refer to the Typical Performance Characteristics curves for power dissipation information at lower output power levels.

POWER SUPPLY BYPASSING

As with any power amplifier, proper supply bypassing is critical for low noise performance and high power supply rejection. Applications that employ a 5V regulator typically use a $10\mu F$ in parallel with a $0.1\mu F$ filter capacitors to stabilize the regulator's output, reduce noise on the supply line, and improve the supply's transient response. However, their presence does not eliminate the need for a local $1.0\mu F$ tantalum bypass capacitance connected between the LM4857's supply pins and ground. Keep the length of leads and traces that connect capacitors between the LM4857's power supply pin and ground as short as possible.

SELECTING EXTERNAL COMPONENTS

Input Capacitor Value Selection

Amplifying the lowest audio frequencies requires a high value input coupling capacitor (C_i in Figure 1). In many cases, however, the speakers used in portable systems, whether internal or external, have little ability to reproduce signals below 50Hz. Applications using speakers with this limited frequency response reap little improvement; by using a large input capacitor.

The internal input resistor (R_i) and the input capacitor (C_i) produce a high pass filter cutoff frequency that is found using Equation (13).

$$f_c = 1 / (2\pi R_i C_i)$$
 (13)

As an example when using a speaker with a low frequency limit of 50Hz and $R_i=20k\Omega,\ C_i,\ using Equation\ (13)$ is 0.19µF. The 0.22µF C_i shown in Figure 4 allows the LM4857 to drive high efficiency, full range speaker whose response extends below 40Hz.

Output Capacitor Value Selection

Amplifying the lowest audio frequencies also requires the use of a high value output coupling capacitor (C_O in Figure 1). A high value output capacitor can be expensive and may compromise space efficiency in portable design.

The speaker load (R_L) and the output capacitor (C_O) form a high pass filter with a low cutoff frequency determined using Equation (14).

$$f_c = 1 / (2\pi R_L C_O)$$
 (14)

When using a typical headphone load of R_L = 32Ω with a low frequency limit of 50Hz, C_O is 99μ F.

The $100\mu F\,C_O$ shown in Figure 4 allows the LM4857 to drive a headphone whose frequency response extends below 50Hz.

Bypass Capacitor Value Selection

Besides minimizing the input capacitor size, careful consideration should be paid to value of CB, the capacitor connected to the BYPASS pin. Since CB determines how fast the LM4857 settles to quiescent operation, its value is critical when minimizing turn-on pops. The slower the LM4857's outputs ramp to their quiescent DC voltage (nominally V_{DD}/ 2), the smaller the turn-on pop. Choosing C_B equal to $2.2\mu F$ along with a small value of Ci (in the range of 0.1µF to 0.39µF), produces a click-less and pop-less shutdown function. As discussed above, choosing C_i no larger than necessary for the desired bandwidth helps minimize clicks and pops. CB's value should be in the range of 5 times to 10 times the value of C_i. This ensures that output transients are eliminated when the LM4857 transitions in and out of shutdown mode. Connecting a 2.2µF capacitor, C_B, between the BYPASS pin and ground improves the internal bias voltage's stability and improves the amplifier's PSRR. The PSRR improvements increase as the bypass pin capacitor value increases. However, increasing the value of $C_{\mbox{\scriptsize B}}$ will increase wake-up time. The selection of bypass capacitor value, CB, depends on desired PSRR requirements, click and pop performance, wake-up time, system cost, and size constraints.

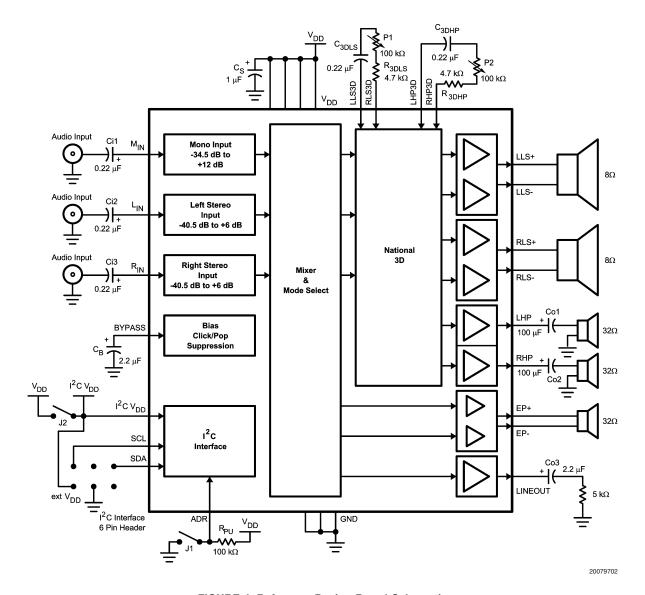
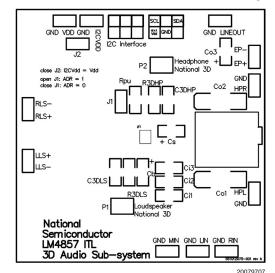
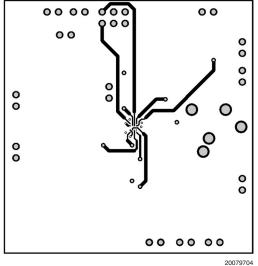


FIGURE 4. Reference Design Board Schematic

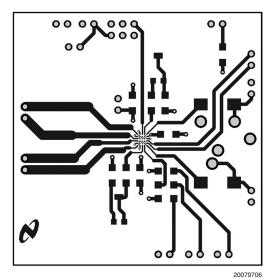
Demonstration ITL/LQ Board Layout



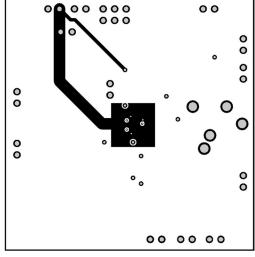
Recommended ITL PCB Layout: Top Silkscreen



Recommended ITL PCB Layout: Inner Layer 1



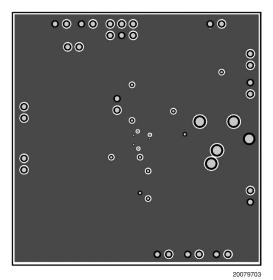
Recommended ITL PCB Layout: Top Layer



20079705

Recommended ITL PCB Layout: Inner Layer 2

Demonstration ITL/LQ Board Layout (Continued)

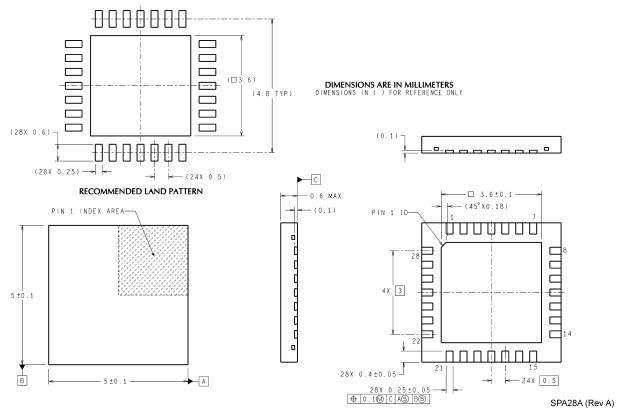


Recommended ITL PCB Layout: Bottom Layer

Physical Dimensions inches (millimeters) unless otherwise noted \oplus \oplus \oplus \oplus \oplus \oplus \oplus \ominus \ominus \ominus ⊕ ⊕ ⊕ ⊕ ⊕ SYMM € \oplus \oplus \ominus \ominus \ominus **DIMENSIONS ARE IN MILLIMETERS** \oplus \oplus \oplus \oplus \oplus (0.5 TYP)-LAND PATTERN RECOMMENDATION SYMM TOP SIDE COATING \oplus \oplus \oplus \oplus \oplus \oplus \oplus \oplus \oplus 0.5 TYP \oplus \oplus \ominus \oplus BUMP A1 CORNER SILICON-À 0.5 TYP 30X Ø 0.31 (a) 0.005 | C AS BS TLA30XXX (Rev B)

30-Bump micro SMD Order Number LM4857ITL NS Package Number TLA30CZA $X_1 = 2.543 \pm 0.03 \; X_2 = 2.949 \pm 0.03 \; X_3 = 0.6 \pm 0.075$

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



28 — Lead SP Package Order Number LM4857SP NS Package Number SPA28A (available soon)

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